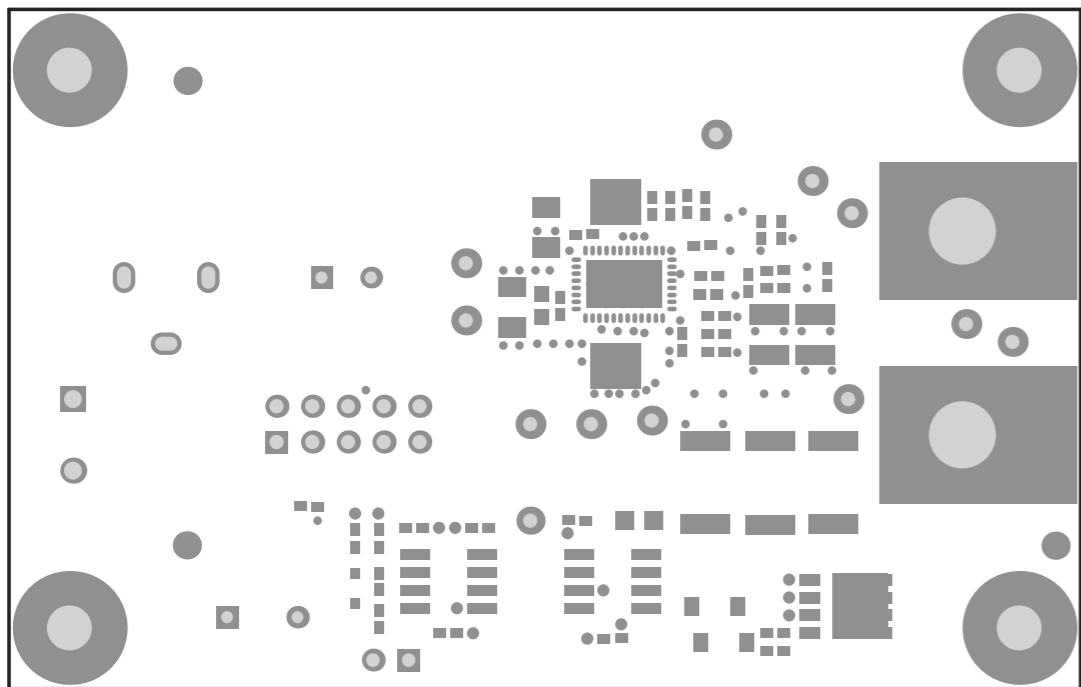
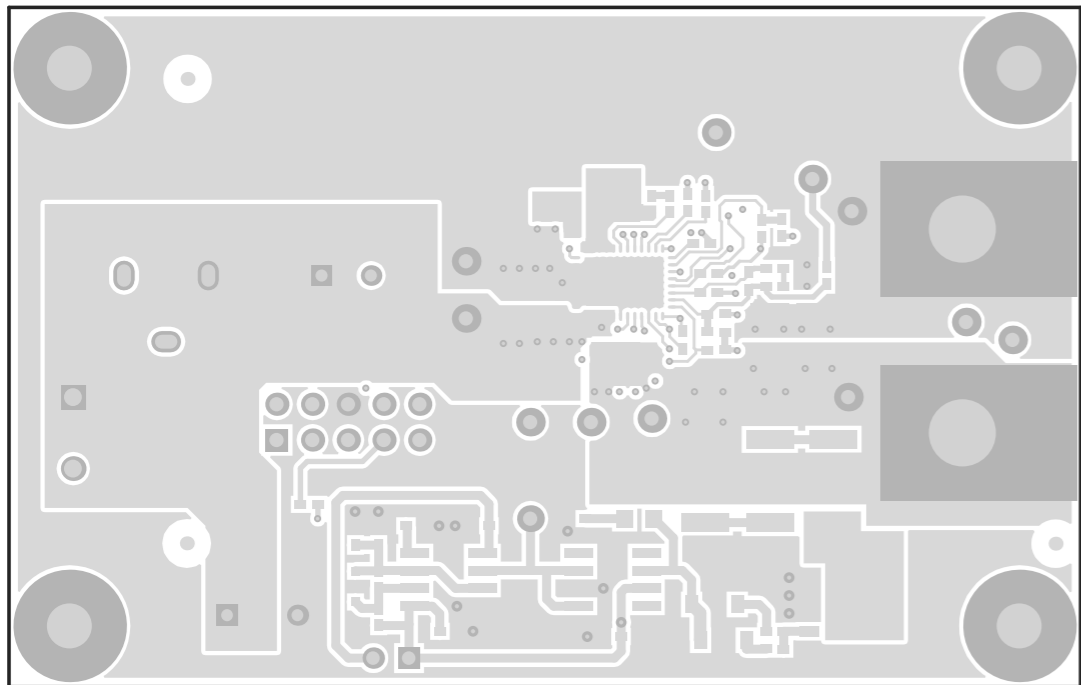


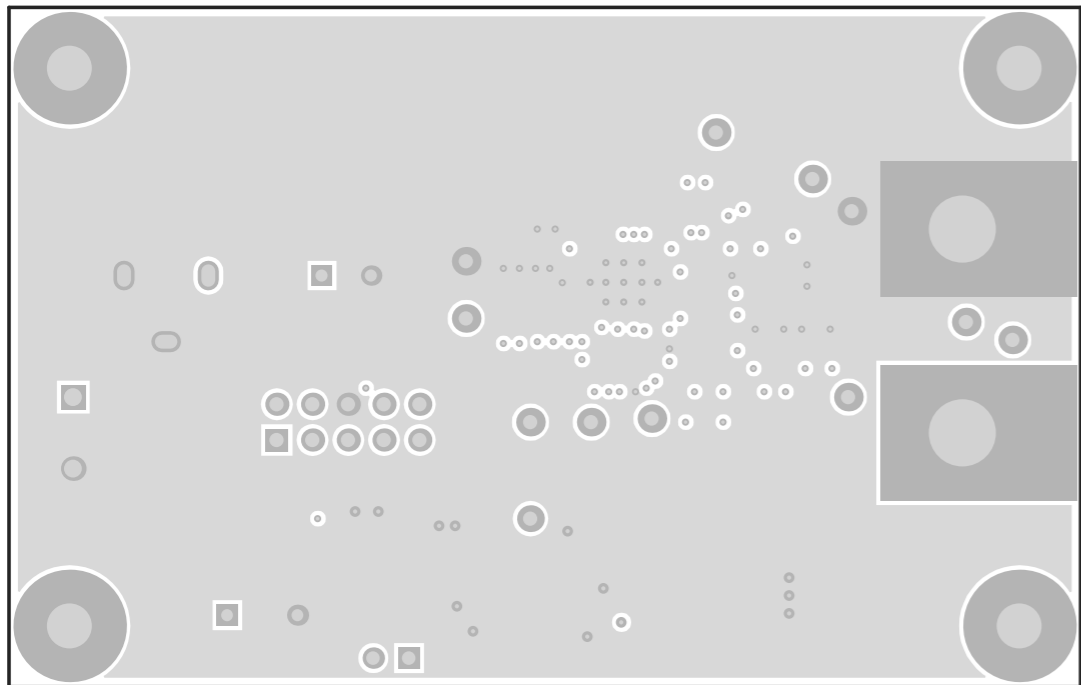
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/4/2014 3:07:15 PM	TEXAS INSTRUMENTS	



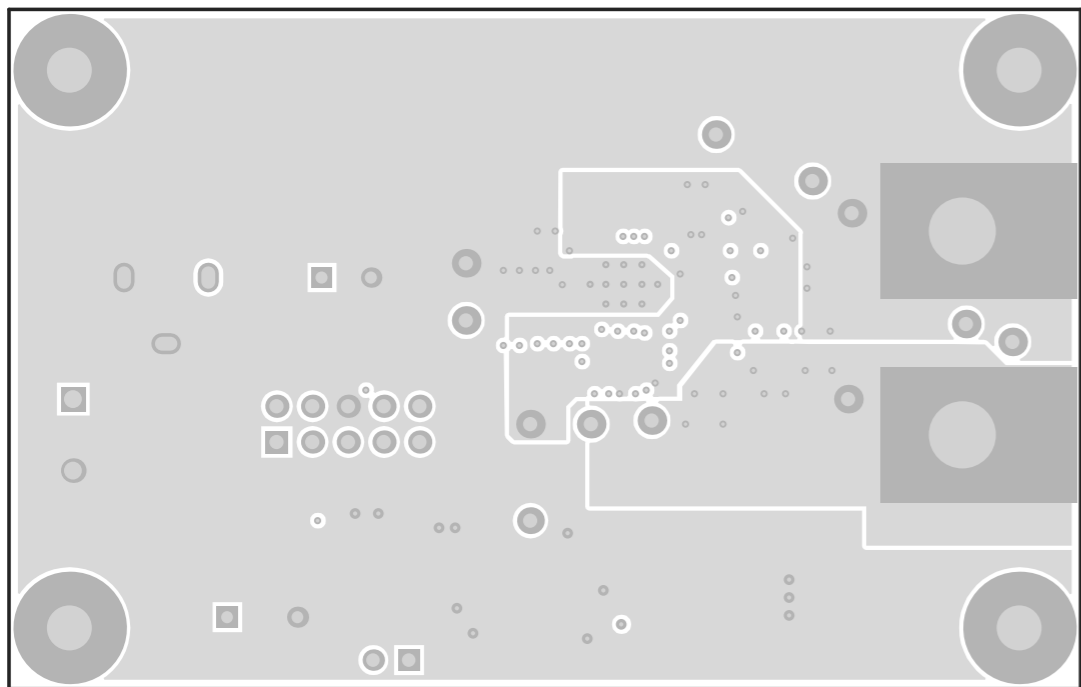
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/4/2014 3:07:16 PM	TEXAS INSTRUMENTS	



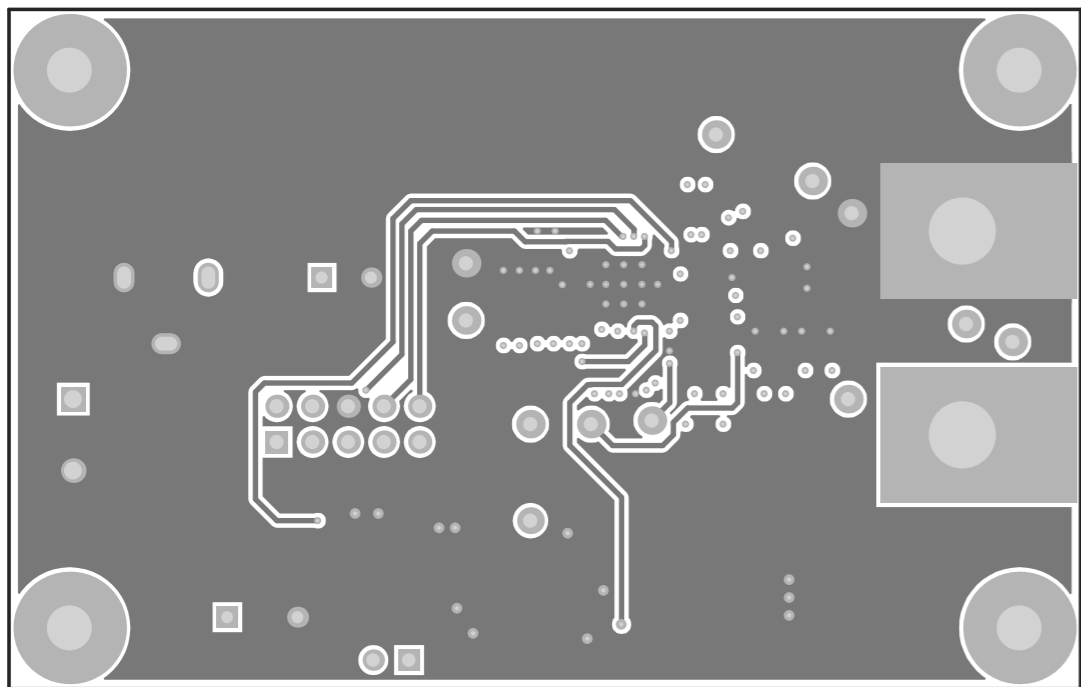
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/4/2014 3:07:17 PM	TEXAS INSTRUMENTS	



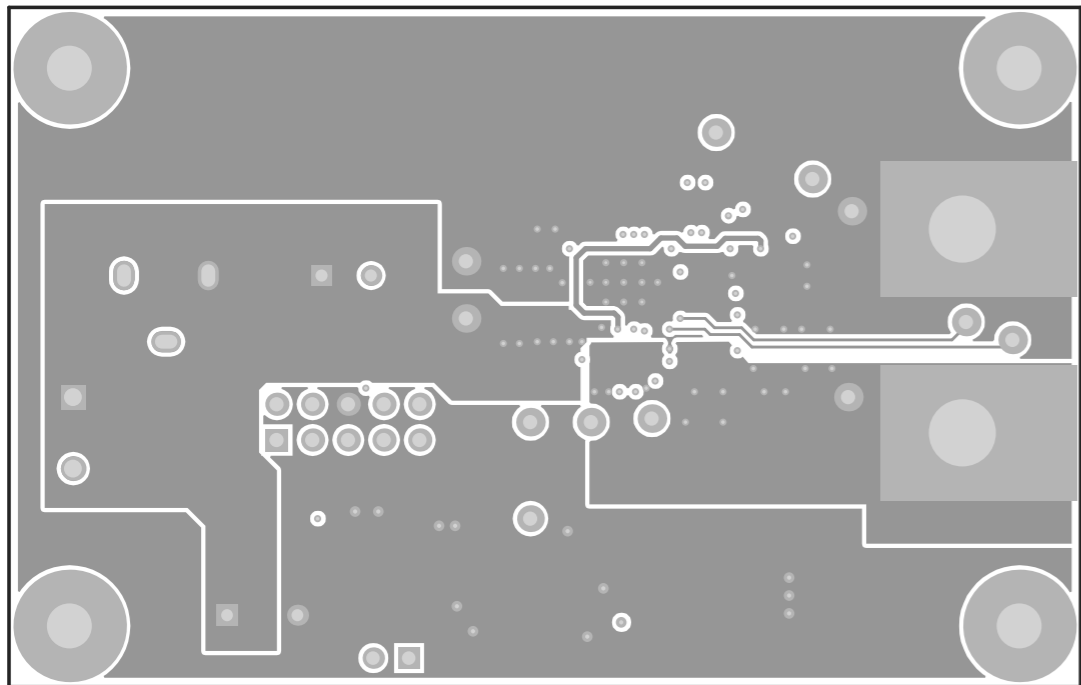
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 9/4/2014 3:07:17 PM	TEXAS INSTRUMENTS	



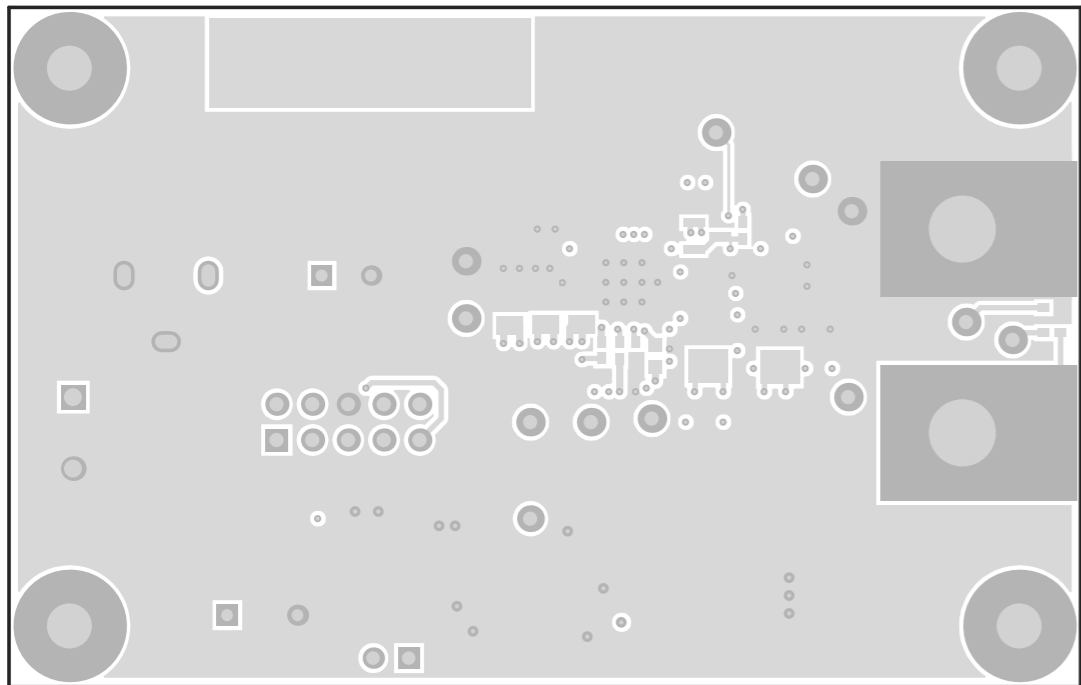
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 9/4/2014 3:07:18 PM	TEXAS INSTRUMENTS	



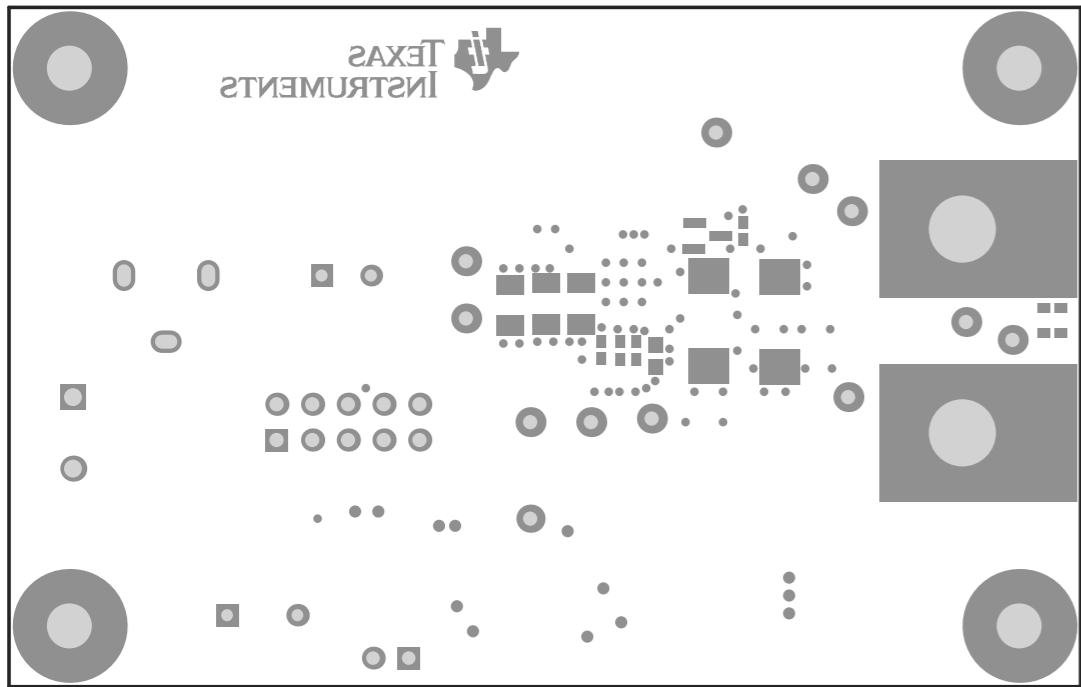
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer3	GENERATED : 9/4/2014 3:07:19 PM	TEXAS INSTRUMENTS	



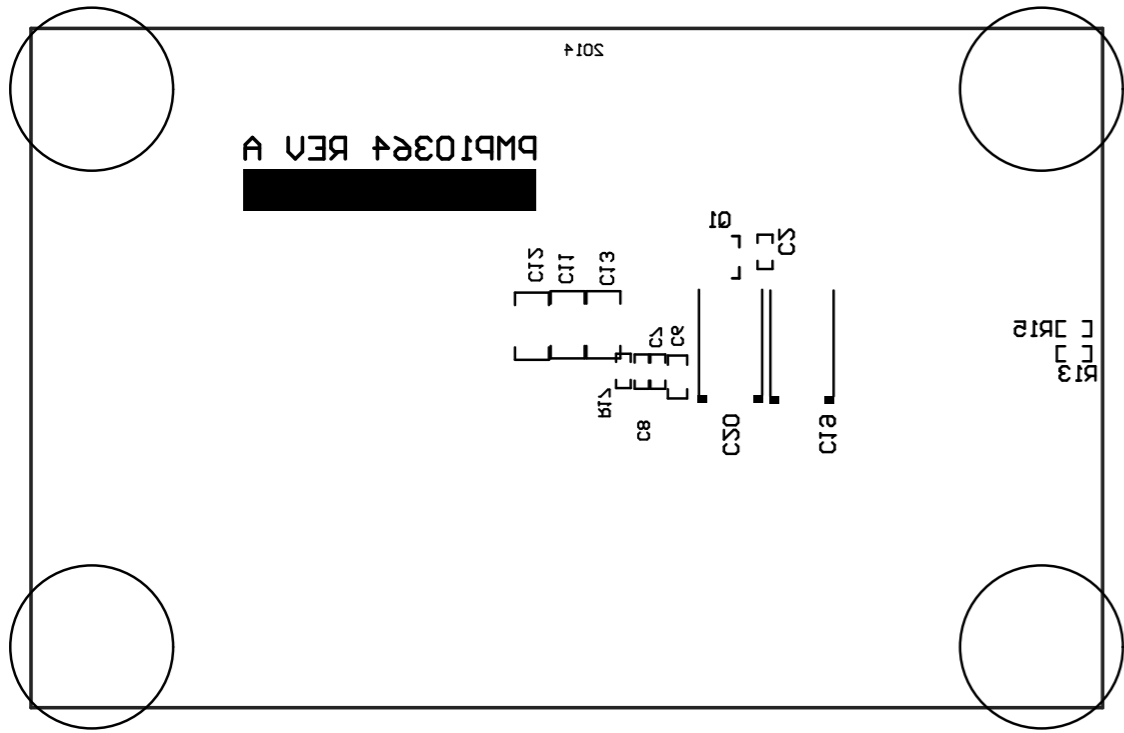
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer4	GENERATED : 9/4/2014 3:07:19 PM	TEXAS INSTRUMENTS	



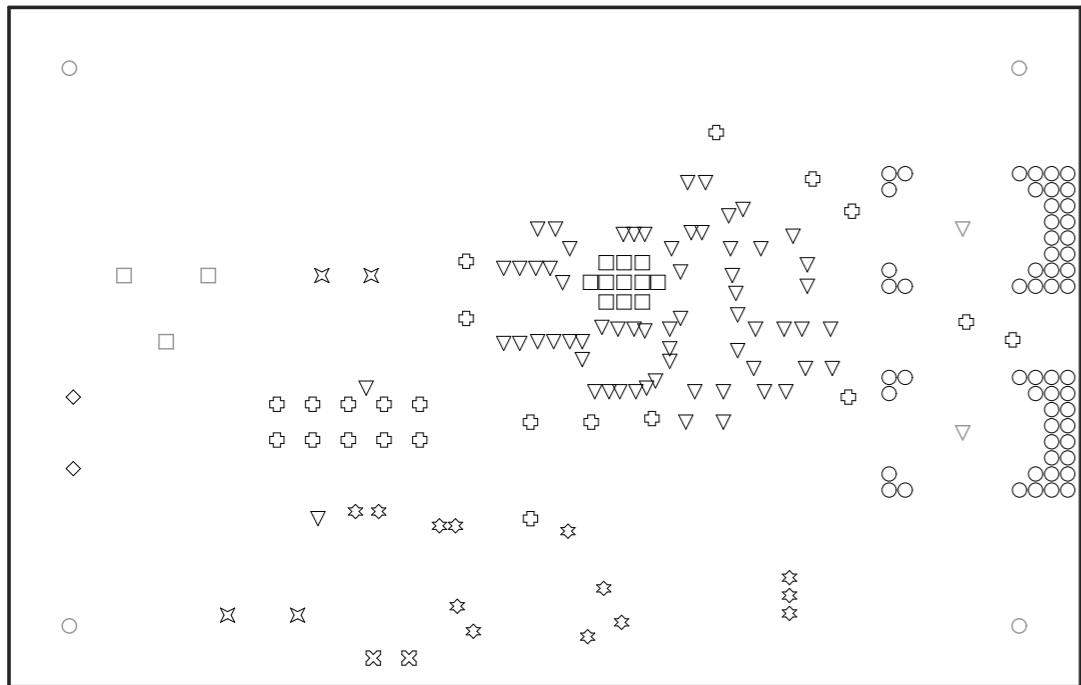
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/4/2014 3:07:20 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/4/2014	3:07:20 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/4/2014 3:07:21 PM	TEXAS INSTRUMENTS	

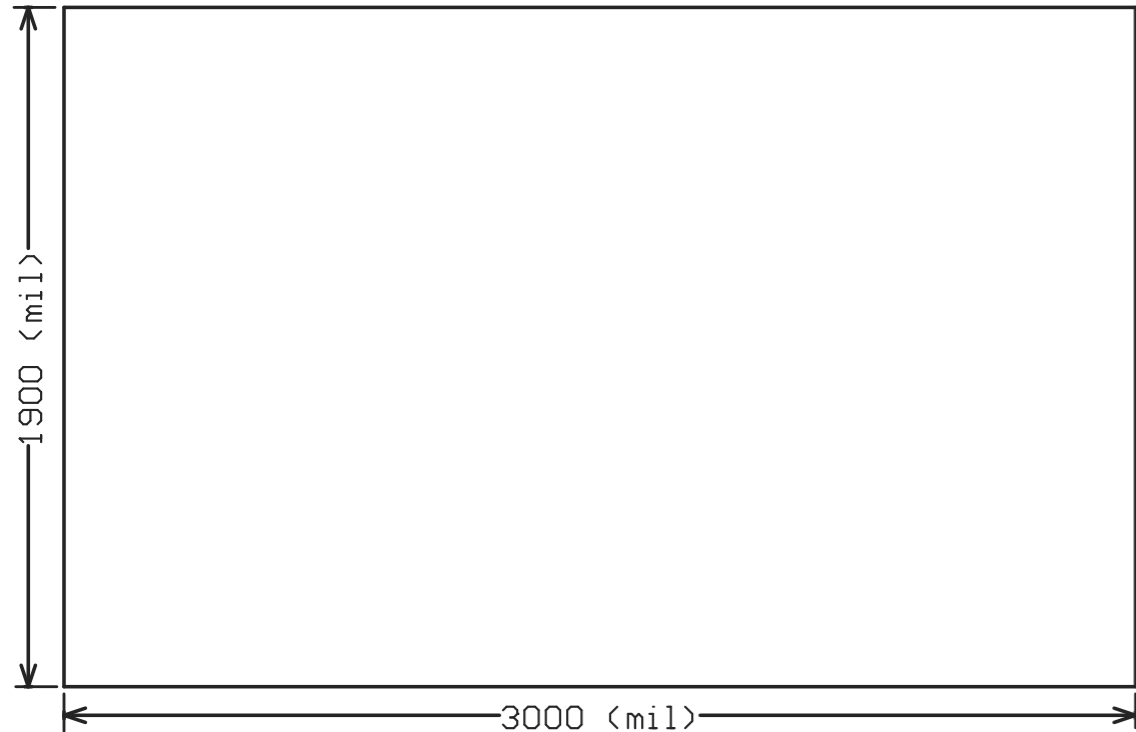


Symbol	Hit Count	Tool Size	Physical Length	R
□	11	7.874mil (0.2mm)		
▽	64	10mil (0.254mm)		
☆	13	12mil (0.305mm)		
○	56	16mil (0.406mm)		
✕	4	33.465mil (0.85mm)		
⊗	2	38mil (0.965mm)		
⊕	22	40mil (1.016mm)		
◇	2	49.213mil (1.25mm)		
○	4	125.984mil (3.2mm)		
▽	2	188mil (4.775mm)		
□	3	39.37mil (1mm)	62.992mil (1.6mm)	2
	183 Total			

Slot definitions : Rout Path Length = Calculated from tool size
 Physical Length = Rout Path Length + Tool Size

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/4/2014	3:07:22 PM	TEXAS INSTRUMENTS



← 1000 (mil) →

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/4/2014 3:07:22 PM	TEXAS INSTRUMENTS	

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